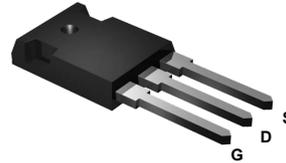
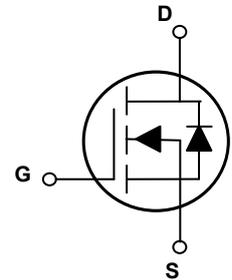


## Main Product Characteristics

$V_{(BR)DSS}$	650V
$R_{DS(ON)}$	41mΩ (Max.)
$I_D$	70A



TO-247



Schematic Diagram

## Features and Benefits

- Advance MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery
- AEC-Q101 qualified



## Description

The GSJA65R041AU utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_J=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	650	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Drain Current-Continuous, @ Steady-State ( $T_C=25^{\circ}\text{C}$ )	$I_D$	70	A
Drain Current-Continuous, @ Steady-State ( $T_C=100^{\circ}\text{C}$ )		46	
Drain Current-Pulsed	$I_{DM}$	260	A
Single Pulse Avalanche Energy <sup>1</sup>	$E_{AS}$	2768	mJ
Power Dissipation ( $T_C=25^{\circ}\text{C}$ )	$P_D$	500	W
		4.0	W/ $^{\circ}\text{C}$
Body Diode Reverse Voltage Slope <sup>2</sup>	dv/dt	50	V/ns
MOS dv/dt Ruggedness <sup>3</sup>	dv/dt	100	V/ns
Junction-to-Ambient (PCB Mounted, Steady-State)	$R_{\theta JA}$	50	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.3	$^{\circ}\text{C}/\text{W}$
Operating Junction Temperature Range	$T_J$	-55 To +175	$^{\circ}\text{C}$
Storage Temperature Range	$T_{STG}$	-55 To +175	$^{\circ}\text{C}$
Soldering Temperature	$T_{SOLD}$	260	$^{\circ}\text{C}$

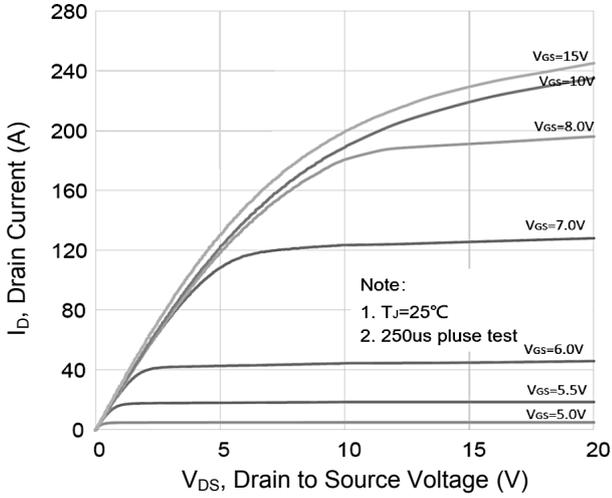
**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	650	-	-	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=650V, V_{GS}=0V, T_J=25^\circ\text{C}$	-	-	6	$\mu A$
		$V_{DS}=650V, V_{GS}=0V, T_J=125^\circ\text{C}$	-	80	-	$\mu A$
Gate-Source Forward Leakage	$I_{GSS}$	$V_{GS}=\pm 30V, V_{DS}=0V$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=35A$	-	37	41	m $\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	3.0	-	5.0	V
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>4,5</sup>	$Q_g$	$V_{DD}=480V, I_D=50A, V_{GS}=10V$	-	326	-	nC
Gate-Source Charge <sup>4,5</sup>	$Q_{gs}$		-	47	-	
Gate-Drain ("Miller") Charge <sup>4,5</sup>	$Q_{gd}$		-	210	-	
Gate to Plateau <sup>4,5</sup>	$V_{plateau}$		-	6.6	-	V
Turn-On Delay Time <sup>4,5</sup>	$t_{d(on)}$	$V_{DD}=400V, R_G=1.8\Omega, V_{GS}=13V, I_D=50A$	-	36	-	nS
Rise Time <sup>4,5</sup>	$t_r$		-	52	-	
Turn-Off Delay Time <sup>4,5</sup>	$t_{d(off)}$		-	208	-	
Fall Time <sup>4,5</sup>	$t_f$		-	47	-	
Input Capacitance	$C_{iss}$	$V_{DS}=100V, V_{GS}=0V, F=1\text{MHz}$	-	7132	-	pF
Output Capacitance	$C_{oss}$		-	284	-	
Reverse Transfer Capacitance	$C_{rss}$		-	5.7	-	
Gate Resistance	$R_g$	$F=1\text{MHz}$	-	1.4	-	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current (Body Diode)	$I_S$	$T_C=25^\circ\text{C}$ , MOSFET symbol showing the integral reverse p-n junction diode.	-	-	70	A
Source Pulse Current	$I_{SM}$		-	-	360	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=50A$	-	-	1.4	V
Reverse Recovery Time <sup>4</sup>	$t_{rr}$	$V_{GS}=0V, I_S=50A, di_f/dt=100A/\mu s$	-	173	-	nS
Reverse Recovery Charge <sup>4</sup>	$Q_{rr}$		-	1.2	-	$\mu C$
Reverse Recovery Peak Current <sup>4</sup>	$I_{rrm}$		-	11	-	A

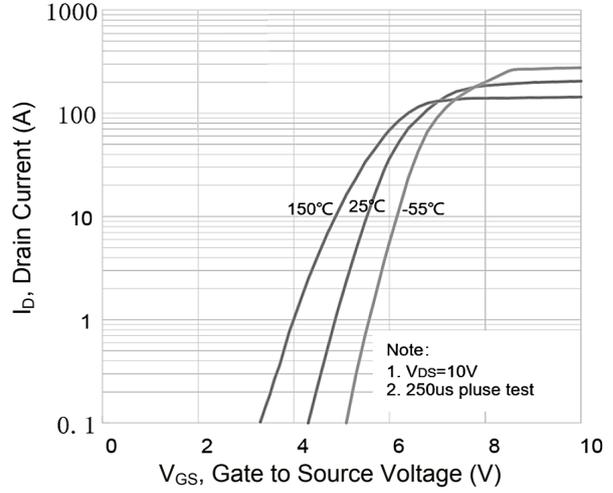
Note:

1.  $L=79\text{mH}, I_{AS}=7.8A, V_{DD}=100V, R_g=25\Omega$ , starting temperature  $T_J=25^\circ\text{C}$ .
2.  $V_{DS}=0-400V, I_{SD} \leq I_S, T_J=25^\circ\text{C}$ .
3.  $V_{DS}=0-400V$ .
4. Pulse test: Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
5. Essentially independent of operating temperature.

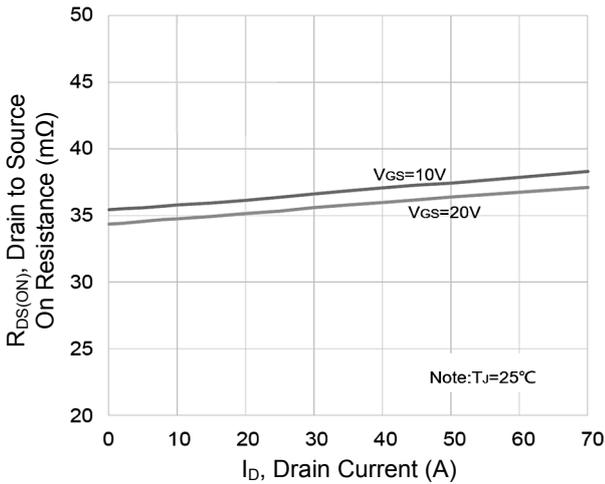
**Typical Electrical and Thermal Characteristic Curves**



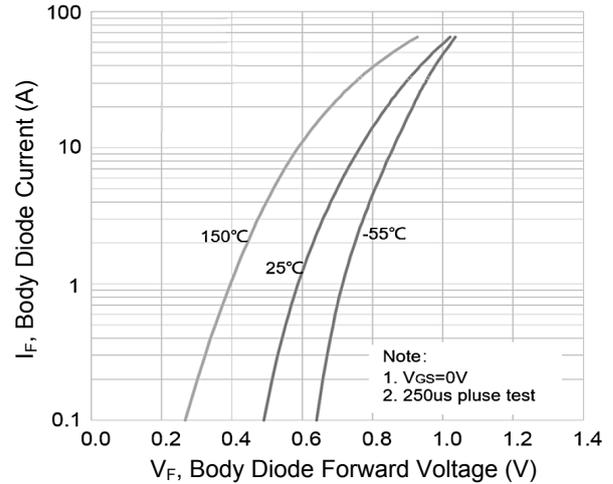
**Figure 1. Typical Output Characteristics**



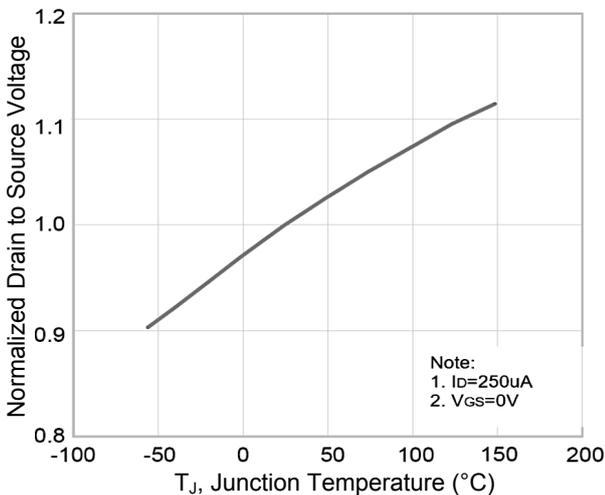
**Figure 2. Transfer Characteristics**



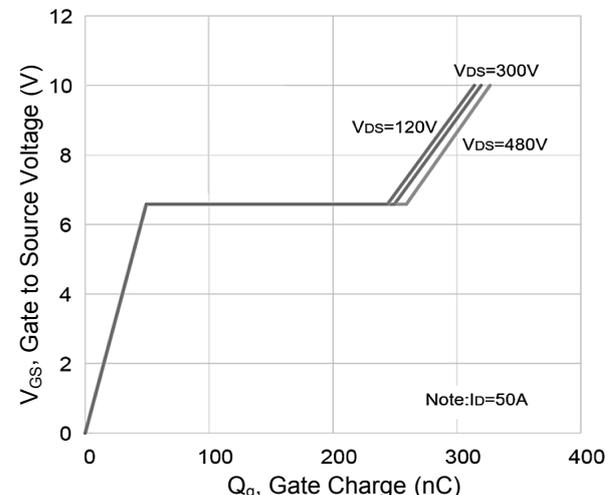
**Figure 3.  $R_{DS(ON)}$  vs. Drain Current**



**Figure 4. Body Diode Characteristics**

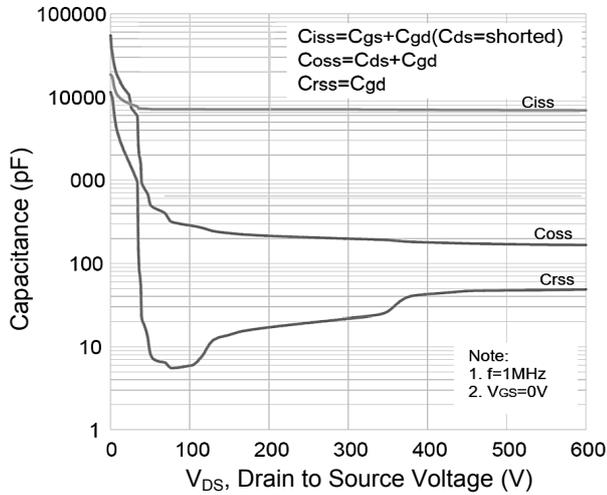


**Figure 5. Normalized  $BV_{DSS}$  vs.  $T_J$**

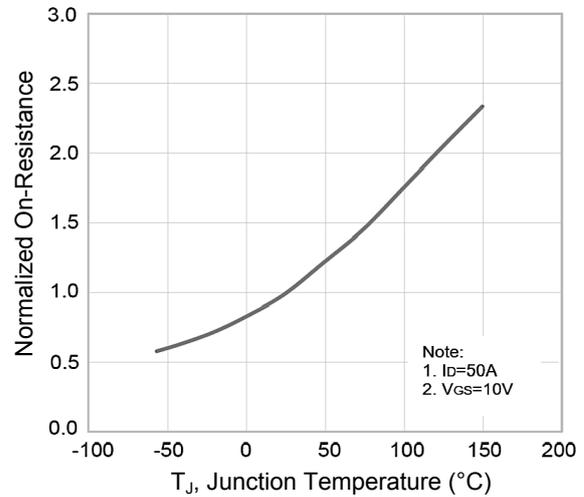


**Figure 6. Gate Charge Characteristic**

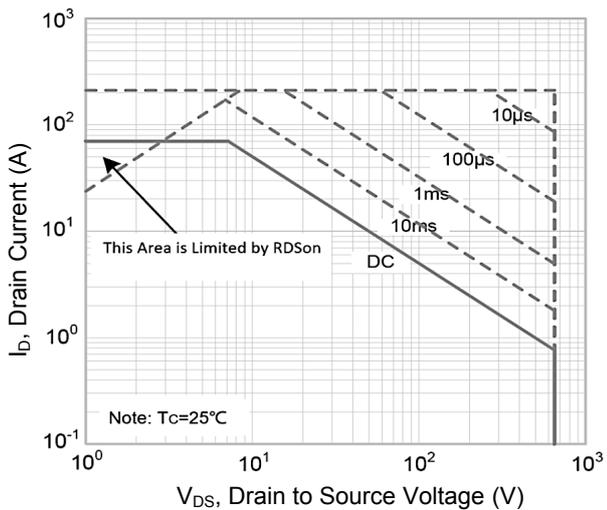
**Typical Electrical and Thermal Characteristic Curves**



**Figure 7. Capacitance Characteristic**

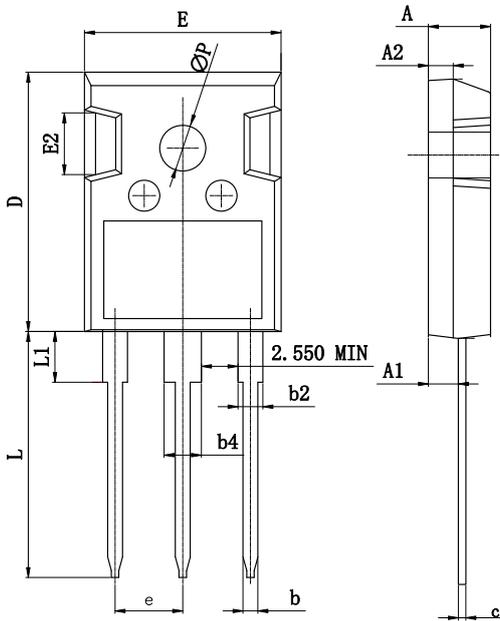


**Figure 8. Normalized  $R_{DS(ON)}$  vs.  $T_J$**



**Figure 9. Safe Operation Area**

**Package Outline Dimensions (TO-247)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.75	5.20	0.187	0.205
A1	2.21	2.65	0.087	0.104
A2	1.85	2.15	0.073	0.085
b	1.00	1.36	0.039	0.054
b2	1.80	2.25	0.071	0.089
b4	2.91	3.25	0.115	0.128
c	0.51	0.75	0.020	0.030
D	20.80	21.30	0.819	0.839
E	15.50	16.10	0.610	0.634
E2	4.40	5.20	0.173	0.205
e	5.44 BSC		0.214 BSC	
L	19.72	20.22	0.776	0.796
L1	-	4.30	-	0.169
P	3.40	3.80	0.134	0.150

**Order Information**

Device	Package	Marking	Packaging	SPQ
GSJA65R041AU	TO-247	A65R041	Tube	30 Pcs / Tube

For more information, please contact us at: [inquiry@goodarksemi.com](mailto:inquiry@goodarksemi.com)